

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,847,105 B2
APPLICATION NO. : 09/960089
DATED : January 25, 2005
INVENTOR(S) : Michel Koopmans

Page 1 of 5

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, section (57):
ABSTRACT, 11th line

change "a bond pad on top semiconductor" to
--a bond pad on the top semiconductor--

In the drawings:

In FIG. 2

insert reference numeral --74-- and associated lead line at top central portion of drawing
insert --(PRIOR ART)-- right below "Fig. 6"
insert --(PRIOR ART)-- right below "Fig. 7"
and insert reference numeral --724-- and associated lead line at the bottom left portion between reference numerals "760" and "728"
insert --(PRIOR ART)-- right below "Fig. 8"
change reference numeral "976" to --974'--
insert reference numeral --1030-- and associated lead line at bottom left portion of drawing
insert reference numeral --930'"-- and associated lead line at bottom right portion of drawing

In FIG. 6

In FIG. 7

In FIG. 8

In FIG. 10

In FIG. 11

In FIG. 14

Replace FIG. 2 with the following:

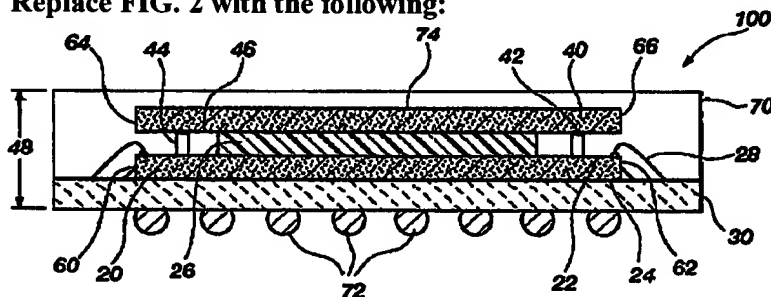


Fig. 2

Replace FIG. 6 with the following:

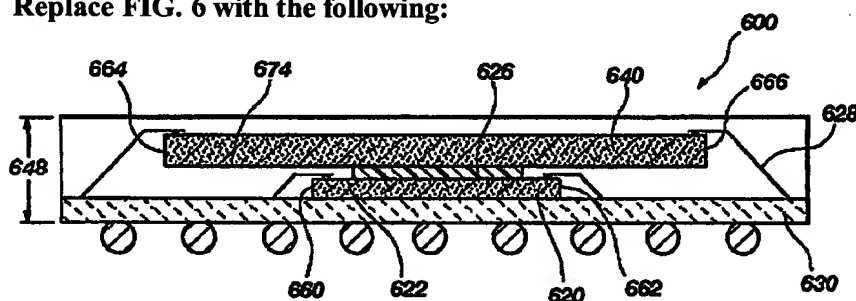


Fig. 6
(PRIOR ART)

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Replace FIG. 7 with the following:

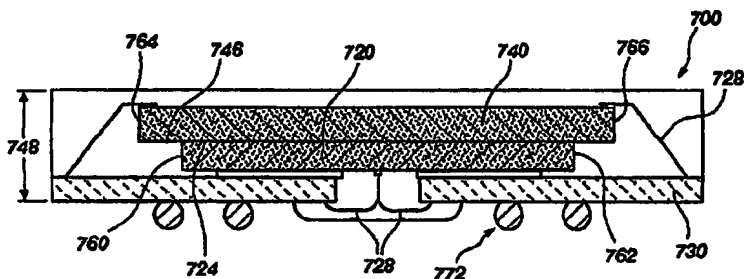


Fig. 7
(PRIOR ART)

Replace FIG. 8 with the following:

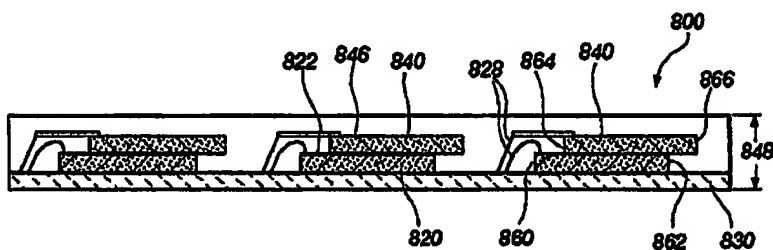


Fig. 8
(PRIOR ART)

Replace FIG. 10 with the following:

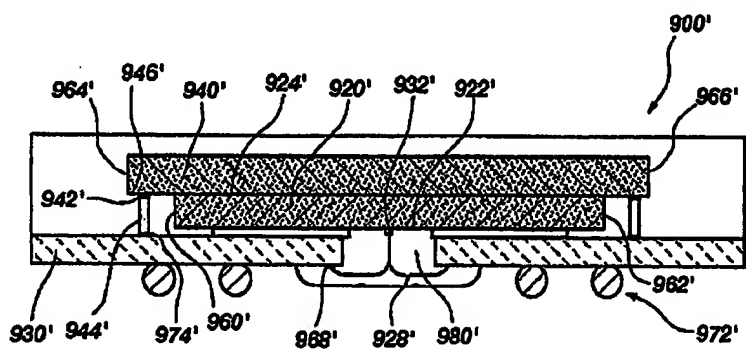


Fig. 10

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Replace FIG. 11 with the following:

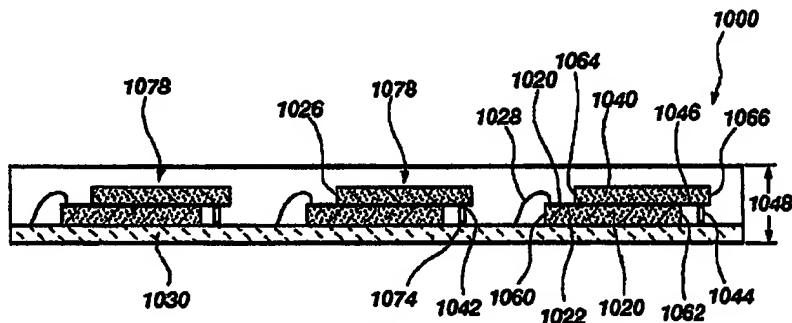


Fig. 11

Replace FIG. 14 with the following:

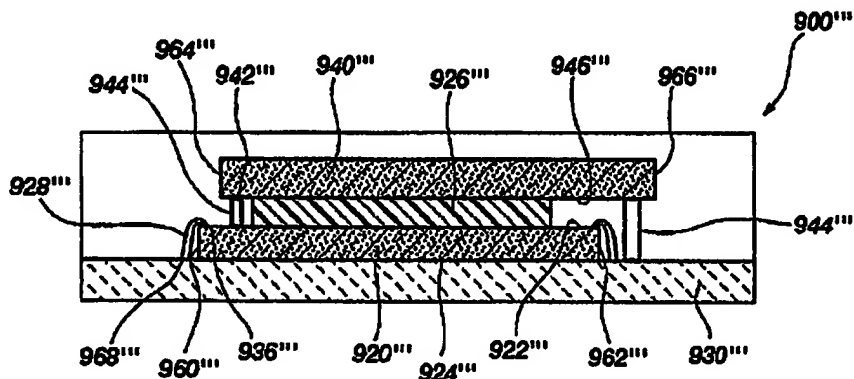


Fig. 14

In the Specification:

COLUMN 1, LINES 49-51,

after "circuit board." delete the remainder of the paragraph (duplicate sentence): "A variation of the pin-in-recess PGA, wherein the loops of the J's are soldered to pads on the surface of the circuit board."

COLUMN 2, LINE 50,
COLUMN 3, LINE 48,
COLUMN 3, LINE 50,
COLUMN 4, LINES 15-16,

change "chip on board" to --chip-on-board--
change "packaged die" to --packaged dice--
change "stacked die" to --stacked dice--
change "corresponding redistribution" to --corresponding first redistribution--

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In the Specification: (cont'd)

COLUMN 4, LINE 20,	change "distance that bond" to --distance so that bond--
COLUMN 4, LINE 21,	change "above an" to --above the--
COLUMN 4, LINES 28-29,	change "bond pad on substrate." to --bond pad on the substrate.--
COLUMN 5, LINE 8,	change "that include" to --that includes--
COLUMN 5, LINE 31,	change "chip type" to --chip-type--
COLUMN 5, LINE 48,	change "additional semiconductor die" to --additional semiconductor dice--
COLUMN 6, LINE 40,	change "having bond pads 430" to --having first redistribution bond pads 430--
COLUMN 6, LINE 42,	change "to the bond" to --to the first redistribution bond--
COLUMN 6, LINE 50,	change "connected, bond" to --connected, first redistribution bond--
COLUMN 7, LINE 15,	change "semiconductor die 20. (FIG. 2)." to --semiconductor die 20 (FIG. 2).--
COLUMN 7, LINE 24,	change "maybe" to --may be--
COLUMN 8, LINE 22,	change "At least one peripheral" to --At least one of the peripheral--
COLUMN 8, LINE 24,	change "least one edge of the peripheral edges" to --least one of the peripheral edges--
COLUMN 8, LINE 28,	change "maybe" to --may be--
COLUMN 9, LINE 16,	change "(e.g. solder," to --(e.g., solder,--
COLUMN 9, LINE 19,	change "semiconductor die" to --semiconductor die--
COLUMN 9, LINE 23,	change "the second die 920"" to --the second semiconductor die 920"--
COLUMN 9, LINE 28,	change "962", 960"" to --966", 964"--
COLUMN 9, LINE 56,	change "conductor filled epoxy," to --conductor-filled epoxy,--
COLUMN 10, LINE 5,	change "of a bottom semiconductor" to --of the top semiconductor--
COLUMN 10, LINE 38,	change "peripheral edge 1064, 1066" to --peripheral edges 1064, 1066--
COLUMN 10, LINE 50,	change "maybe" to --may be--
COLUMN 10, LINE 57,	change "conductor filled epoxy," to --conductor-filled epoxy,--
COLUMN 10, LINE 63,	change "maybe" to --may be--

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In the claims:

CLAIM 12, COLUMN 12, LINE 32-33, change "bond pad is electrically" to --bond pad of said at least one redistribution bond pad circuit is electrically--
CLAIM 24, COLUMN 13, LINE 34, change "semiconductor die are all electrically" to --semiconductor die are electrically--

Signed and Sealed this
Twenty-fourth Day of July, 2007

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looping initial "J" and a distinct "D".

JON W. DUDAS
Director of the United States Patent and Trademark Office